

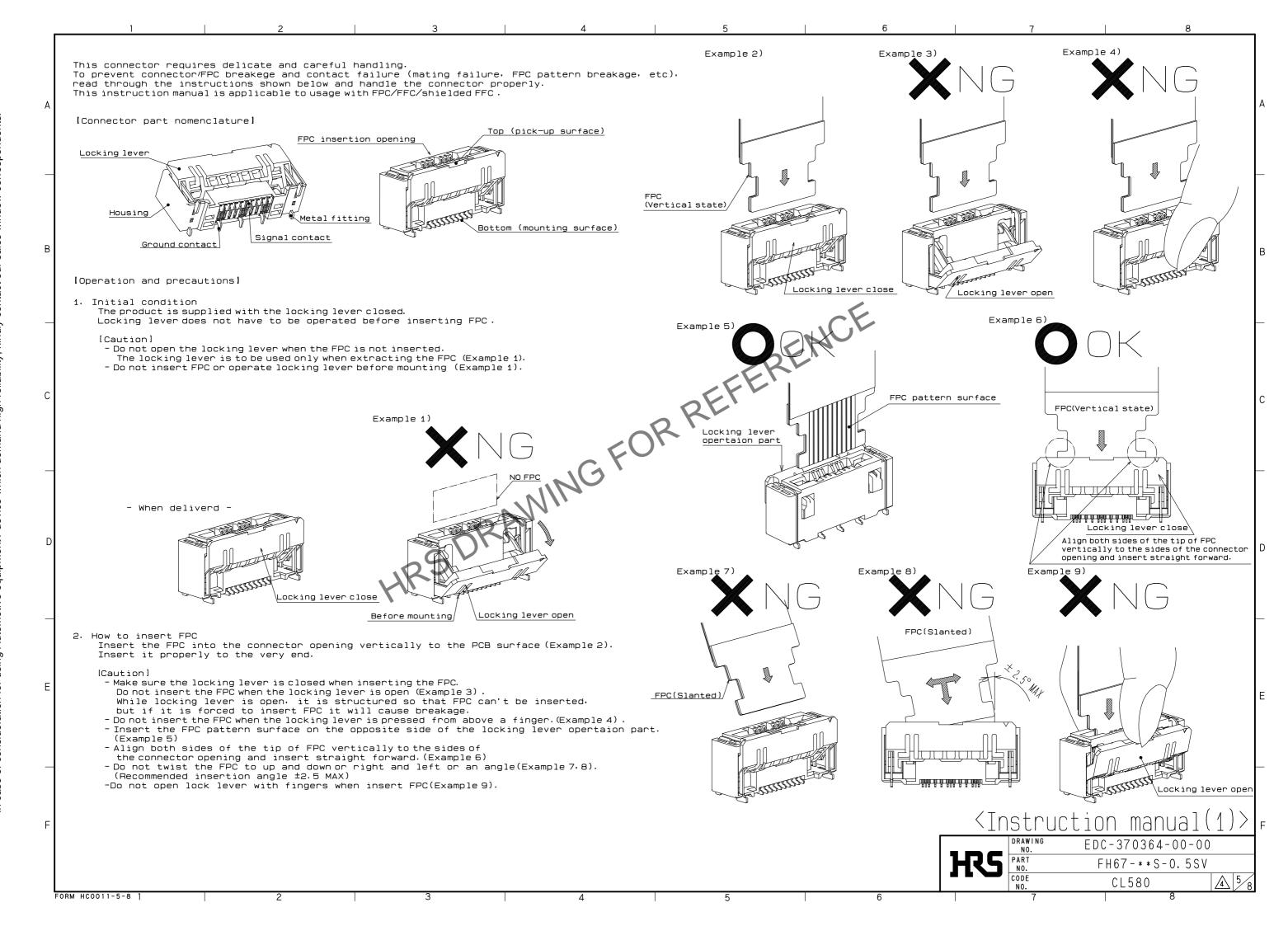
Part No.	Code Number	Number of contacts	Dimension of connector, PCB mounting pattern, metal mask, FPC, FFC, and shielded FFC								Dimension of drawing for packing								
i dii ivo.			Α	В	<u> C</u>	D	E	F	G	Н	J	K	L	M	Р	Q	R	S	U
FH67-10S-0.5SV		10	7.15	4	5	2	11.08	4.5	9.5	3	7.1	5.5	9.1	4.9	24	_	11.5	29.4	25.4
FH67-12S-0.5SV		12	8.15	5	5.5	1.5	12.08	5.5	10.5	4	8.1	6.5	10.1	5.9	24	_	11.5	29.4	25.4
FH67-14S-0.5SV		14	9.15	6	6	2	13.08	6.5	11.5	4	9.1	7.5	11.1	6.9	32	28.4	14.2	37.4	33.4
FH67-16S-0.5SV		16	10.15	7	6.5	1.5	14.08	7.5	12.5	5	10.1	8.5	12.1	7.9	32	28.4	14.2	37.4	33.4
FH67-18S-0.5SV		18	11.15	8	7	2	15.08	8.5	13.5	5	11.1	9.5	13.1	8.9	32	28.4	14.2	37.4	33.4
FH67-20S-0.5SV		20	12.15	9	7.5	1.5	16.08	9.5	14.5	6	12.1	10.5	14.1	9.9	32	28.4	14.2	37.4	33.4
FH67-22S-0.5SV		22	13.15	10	8	2	17.08	10.5	15.5	6	13.1	11.5	15.1	10.9	44	40.4	20.2	49.4	45.4
FH67-24S-0.5SV		24	14.15	11	8	1.5	18.08	11.5	16.5	7	14.1	12.5	16.1	11.9	44	40.4	20.2	49.4	45.4
FH67-26S-0.5SV		26	15.15	12	8	2	19.08	12.5	17.5	7	15.1	13.5	17.1	12.9	44	40.4	20.2	49.4	45.4
FH67-28S-0.5SV		28	16.15	13	8	1.5	20.08	13.5	18.5	8	16.1	14.5	18.1	13.9	44	40.4	20.2	49.4	45.4
FH67-30S-0.5SV	CL580-4901-0-00	30	17.15	14	8	2	21.08	14.5	19.5	8	17.1	15.5	19.1	14.9	44	40.4	20.2	49.4	45.4
FH67-32S-0.5SV		32	18.15	15	8	1.5	22.08	15.5	20.5	9	18.1	16.5	20.1	15.9	44	40.4	20.2	49.4	45.4
FH67-34S-0.5SV		34	19.15	16	8	2	23.08		215	9	19.1	17.5	21.1	16.9	44	40.4	20.2	49.4	45.4
FH67-36S-0.5SV		36	20.15	17	8	1.5	24.08	47.5	22.5	10	20.1	18.5	22.1	17.9	44	40.4	20.2	49.4	45.4
FH67-38S-0.5SV		38	21.15	18	8	2	25.08	18.5	23.5	10	21.1	19.5	23.1	18.9	44	40.4	20.2	49.4	45.4
FH67-40S-0.5SV		40	22.15	19	17	1.5	26.08	19.5	24.5	11	22.1	20.5	24.1	19.9	44	40.4	20.2	49.4	45.4
FH67-42S-0.5SV		42	23.15	20	17	2	27.08	20.5	25.5	11	23.1	21.5	25.1	20.9	44	40.4	20.2	49.4	45.4
FH67-44S-0.5SV		44	24.15	21	17	1.5	28.08	21.5	26.5	12	24.1	22.5	26.1	21.9	44	40.4	20.2	49.4	45.4
FH67-46S-0.5SV		46	25.15	22	43	2	29.08	22.5	27.5	12	25.1	23.5	27.1	22.9	56	52.4	26.2	61.4	57.4
FH67-48S-0.5SV		48	26.15	23	17	1.5	30.08	23.5	28.5	13	26.1	24.5	28.1	23.9	56	52.4	26.2	61.4	57.4
FH67-50S-0.5SV		50	27.15	24	17	2	31.08	24.5	29.5	13	27.1	25.5	29.1	24.9	56	52.4	26.2	61.4	57.4
FH67-52S-0.5SV			28.15	25	17	1.5	32.08	25.5	30.5	14	28.1	26.5	30.1	25.9	56	52.4	26.2	61.4	57.4
FH67-54S-0.5SV			29.15	26	17	2	33.08	26.5	31.5	14	29.1	27.5	31.1	26.9	56	52.4	26.2	61.4	57.4
FH67-56S-0.5SV	1	256	30.15	27	17	1.5	34.08	27.5	32.5	15	30.1	28.5	32.1	27.9	56	52.4	26.2	61.4	57.4
FH67-58S-0.5SV	Y	58	31.15	28	17	2	35.08	28.5	33.5	15	31.1	29.5	33.1	28.9	56	52.4	26.2	61.4	57.4
FH67-60S-0.5SV		60	32.15	29	17	1.5	36.08	29.5	34.5	16	32.1	30.5	34.1	29.9	56	52.4	26.2	61.4	57.4

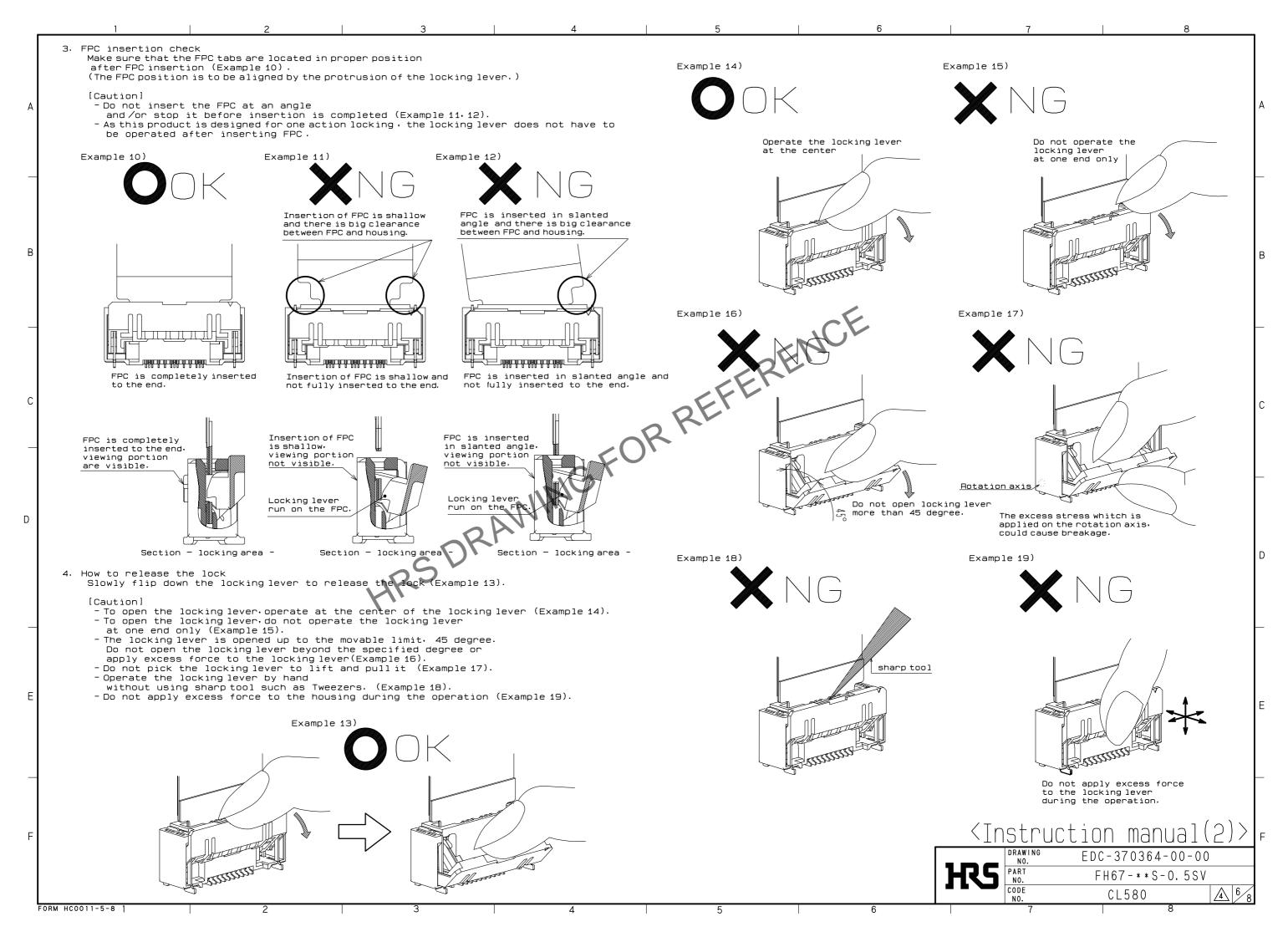
%The products without code number are currently under planning.
Please contact HIROSE for detailed information about product variation.

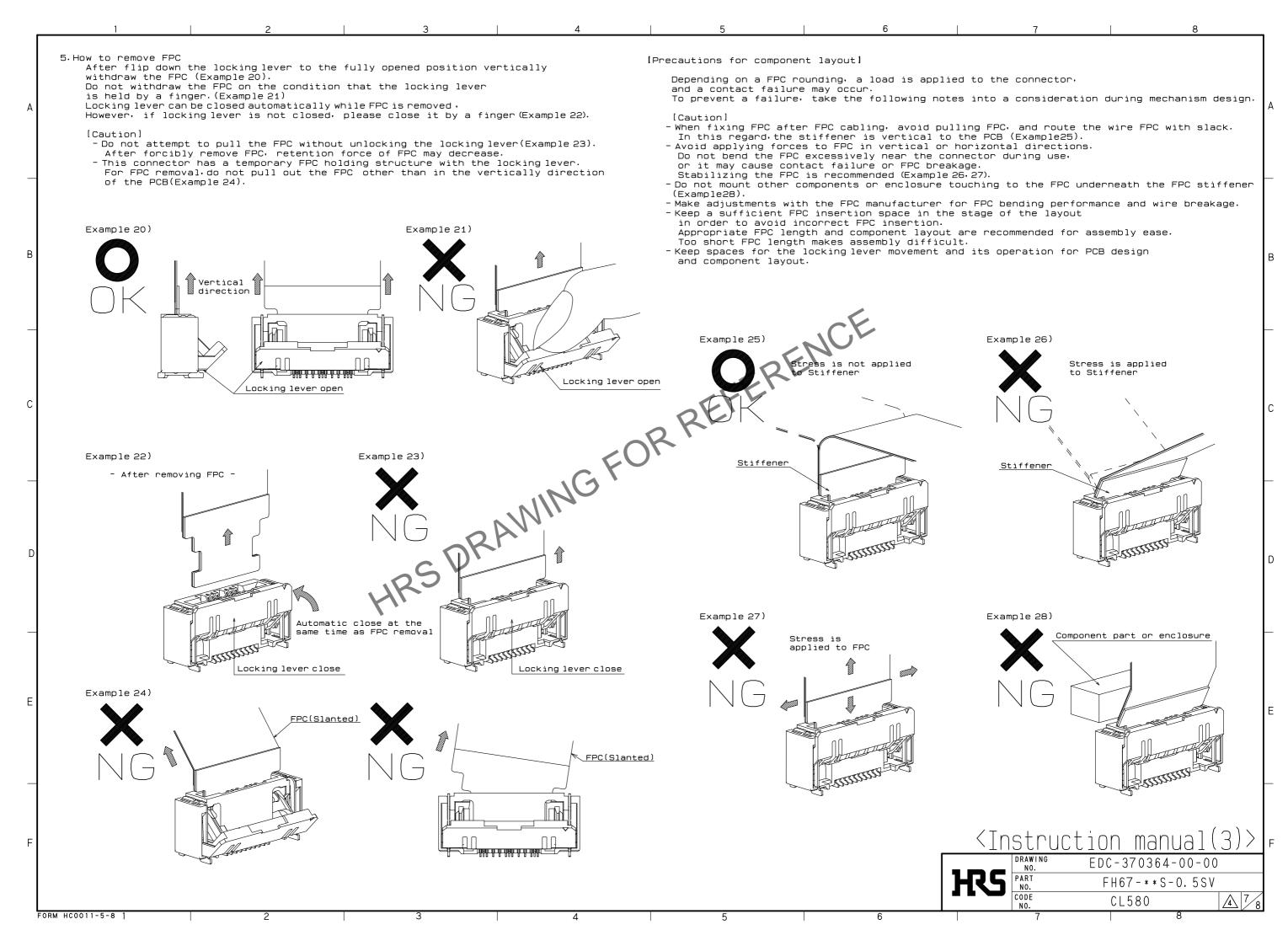
<Dimension table>

Г	HRS	DRAWING NO.	EDC-370364-00-00		
l		PART NO.	FH67-**S-0.5SV		
•		CODE NO.	CL580	4	4/8
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ORM HC0011-5-8 1 2 3 1 1 5







| Recommended reflow temperature profile | 4 | Instructions for mounting on the PCB| Follow the instructions shown below when mounting on the PCB. The temperatures mentioned above refer to the PCB surface temperature near the connector leads. In individual applications the actual temperature may vary, - Refer to recommended layouts on the page 1 for PCB and stencil pattern. depending on solder paste type volume/thickness and board size/thickness. - Shorter pattern width than the recommended PCB dimension. Consult your solder paste and equipment manufacturer for specific recommendations. could cause solder wicking and/or flux penetration. - Larger pattern than the recommended stencil dimension. - Reflow method:IR reflow could cause solder wicking and/or flux penetration. - Number of reflow cycles:2 cycles MAX. - Clearance underneath the contact lead and the housing is very small. In case solder resist and/or silk screening are applied on PCB underneath the connector verify the thickness, or it could push up the connector bottom and may cause soldering defect and/or insufficient fillet formation.

Apply reflow temperature profile within the specified conditions.

In individual applications, the actual temperature may vary. MAX 250 ℃ depending on solder paste type volume/thickness and PCB size/thickness.

Consult your solder paste and equipment manufacturer for specific recommendations. - Prevent warpage of PCB, where possible, since it can cause soldering failure ; even with 0.1 mm max coplanarity. 245 - When mounting on the flexible board, please make sure to put a stiffener on the backside of the flexible board. 220 We recommend a glass epoxy material with the thickness of 0.3 mm min. Example 29)

...y on the PCB.

...y on the PCB. 180 °C - Do not add 1.0 N or greater external force when unreel or pick and place the connector etc. |Instructions for PCB handling after mounting the connector| Follow the instructions shown below when mounting on the PCB. [Caution] С

MAX

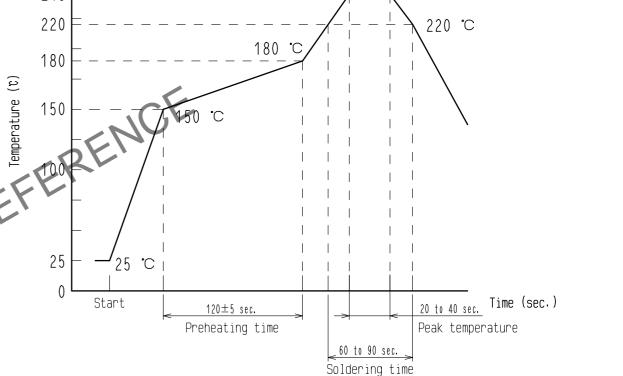
| Instructions on manual soldering

Follow the instructions shown below when soldering the connector manually during repair work, etc.

[Caution]

- Do not perform manual soldering with the FPC inserted into the connector.
- Do not heat the connector excessively. Be very careful not to let the soldering iron contact any parts other than connector leads. Otherwise, the connector may be deformed or melt.
- Do not supply excessive solder (or flux).

 If excessive solder (or flux) is supplied on the terminals, solder or flux may adhere to the contacts, resulting in poor contact . Supplying excessive solder to the metal fittings may hinder locking lever rotation-resulting in breakage of the connector.



<Instruction manual</pre> DRAWING NO. EDC-370364-00-00

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FH67-**S-0.5SV CL580

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